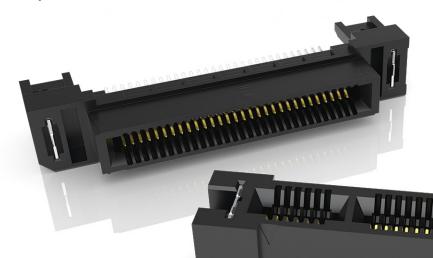


HIGH-SPEED EDGE CARD SYSTEMS

0.60 mm, 0.80 mm and 1.00 mm PITCH



FEATURES & BENEFITS

- Maximum Design Flexibility
- Up to 64 Gbps PAM4 performance
- PCI Express® 3.0, 4.0, 5.0 and 6.0
- Edge Rate[®] contacts optimized for signal integrity performance and high-cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available



Rugged tucked beam technology (HTEC8)



Differential pair for increased speed (HSEC8-DP)



Custom designs allow for misalignment in the X-Y axes (HSEC1)

KEY SPECIFICATIONS

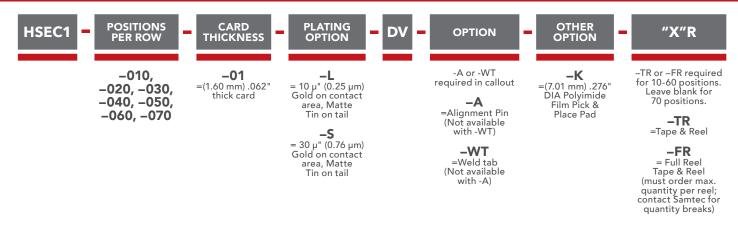
SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	1.9 A (2 pins)	240 VAC	Yes
HTEC8	0.80 mm	20-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC	Yes
HSEC8	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC	Yes





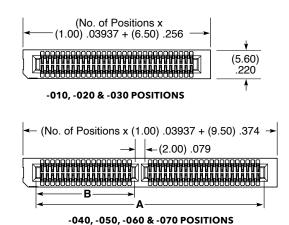


1.00 mm (.0394") PITCH • VERTICAL HIGH-SPEED EDGE CARD

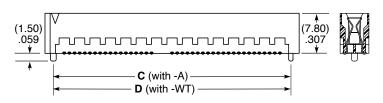


HSEC1-DV Card Mates: (1.60 mm) .062" thick card









POSITIONS PER ROW	A	В	C (with -A)	D (with -WT)
-010	(11.30) .445	N/A	(13.25) .522	(14.50) .571
-020	(21.30) .839	N/A	(23.25) .915	(24.50) .965
-030	(31.30) 1.232	N/A	(33.25) 1.309	(34.50) 1.358
-040	(44.30) 1.744	(19.15) .754	(46.25) 1.821	(47.50) 1.870
-050	(54.30) 2.138	(24.15) .951	(56.25) 2.215	(57.50) 2.264
-060	(64.30) 2.531	(29.15) 1.148	(66.25) 2.608	(67.50) 2.657
-070	(74.30) 2.925	(34.15) 1.344	(76.25) 3.002	(77.50) 3.051

Note:

Some sizes, styles and options are non-standard, non-returnable.

View complete specifications at: samtec.com?HSEC1-DV